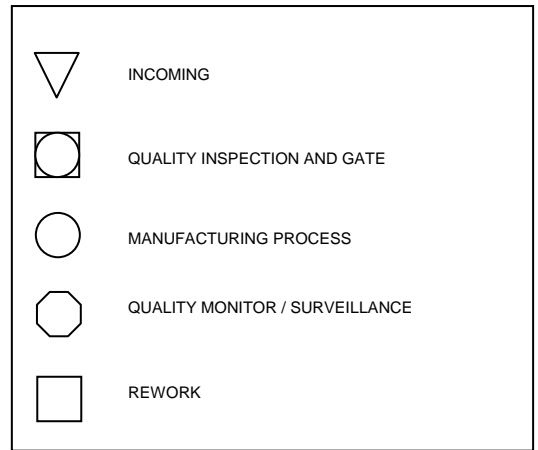





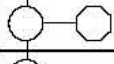

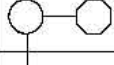



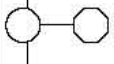


ASSEMBLY FLOWCHART
SOT23 PACKAGE
 Updated 08/25/08

Vendor: Linear Technology Corporation
 Package: SOT 23 Package
 Assembly: LTC Penang Malaysia
 Final Test: Linear Technology Corp., Milpitas, CA.,& Singapore
 Q.C. Test: Linear Technology Corp., Milpitas, CA.,& Singapore
 Source Accept Test: Linear Technology Corp., Milpitas, CA.,& Singapore
 Quality Contact: Naib Girn, LTC Milpitas, CA
 (408) 432-1900 Ext. 2519



Flow Chart Incoming Assy Rework	Process Step	Description	Inspection / Test Criteria	Method / Equipment	Sampling Plan	SPC Technique
	Wafer inventory	Wafer preparation				
	Wafer mount /cure	Wafer inspection	Spec No : 05-03-0501			
	Wafer saw / clean	Die preparation	Spec NO : 05-03-0502	Auto saw		
	Wafer saw monitor	Visual	Spec No : 06-02-0502	10x – 30x scope	Every lot – 1 wafer set up check	% defective log
	2 nd optical inspection	Die quality	Spec No : 05-03-0503 05-03-2039	75x – 150x microscope	Every lot 100% basis	Yield analysis %
	QA 2 nd optical lot acceptance		Spec No : 06-02-0503 05-03-2039	75x – 150x microscope	Sample size 32 0/1 per lot	LAR and % unit defective trend chart
	Lead frame inventory	Lead frame preparation				
	QA incoming lead frame buy-off		Spec No : 06-01-0507 01-07-0002			


Revision A

Flow Chart Incoming Assy Rework	Process Step	Description	Inspection / Test Criteria	Method / Equipment	Sampling Plan	SPC Technique
	Epoxy inventory					
	QA incoming epoxy buy-off		Spec no : 06-01-0505			
	Die attach	Die bonded to lead frame with epoxy	Spec no: 05-03-0504	Auto die bonder		
	Die attach monitor		Spec no : 06-02-0504	10x – 30x microscope	1 strip / magazine	np chart
	Epoxy Cure	Die attach epoxy cure	Spec no : 05-03-0505	Oven		
	QA monitoring	Cure quality	Spec no : 06-02-0505	Die shear tester	1x/shift/machine	X-bar-R chart
	Gold wire inventory					
	QA incoming gold wire buy-off		Spec no : 06-01-0509			
	Wire bond	Ball bonds gold 1.00 mil wire	Spec no : 05-03-0506	Auto thermo-sonic ball bonder		
	Wire bond monitor	Bond pull strength Bond shear strength	Spec no : 06-02-0506 06-02-0507	10x – 30x microscope Ball shear tester Wire pull test	1 strip / magazine Every lot	np chart X-bar-R chart
	100% 3 rd optical inspection	Check for workmanship quality prior to molding	Spec no : 05-03-0508 05-03-0524 P05-03-3042	30x – 60x microscope	Every lot	Yield chart
	QA 3 rd optical inspection	Die, die bond, wire bond visual quality	Spec no : 06-02-0508 P05-03-3042	30x – 60x microscope	Every lot – Sample size 125 0/1	LAR log PPM trend chart

Revision A

Flow Chart Incoming Assy Rework	Process Step	Description	Inspection / Test Criteria	Method / Equipment	Sampling Plan	SPC Technique
	Mold compound inventory					
	QA incoming mold compound buy-off		Spec no: 06-01-0513 01-99-0006			
	Molding		Spec no : 05-03-0511	Transfer mold		
	Mold monitor	Molding quality	Spec no: 06-02-0511 Moldability defects, package offset etc.	10x min microscope	1x per shift per machine	np chart
	Deflash Blank		Spec no : 05-03-0520			
	Deflash / Blank Monitor	Visual / mechanical Delamination	Spec no : 06-02-0520	30x microscope Scanning acoustic microscope	Min 1 lot per shift per machine Min 2 lots per shift per machine	np chart
	Bottom Mark	Traceability, device marking	Spec no : 05-03-0528 05-03-4601			
	Laser top mark		Spec no: 05-03-0528 05-03-8000	Min 3x scope	Every lot – 2 strips minimum	Log
	Laser top mark monitor	Marking quality	Spec no: 06-02-0519			
	Solder inventory					
	QA incoming Solder buyoff		Spec no : 06-01-0517			
	Solder plate	Lead finish	Spec no: 05-03-0518	Auto strip plater	1 lot per package per shift	Log
	Solder plate monitor	Solderability, solder composition and thickness	Spec no: 06-02-0518	7x – 30x microscope XRF equipment	3 lots per machine per shift	Log X-bar-R chart
	QA X-ray gate		Spec no : 06-02-0512	X-ray equipment	Every lot – 20 0/1	QA Log

Revision A

Flow Chart Incoming Assy Rework	Process Step	Description	Inspection / Test Criteria	Method / Equipment	Sampling Plan	SPC Technique
	Strip inspection	100% inspection	Spec no: 05-03-0519 P05-03-8082	3x scope		Log
	QA lot acceptance	Gate	Spec no: 06-02-0518	3x scope	Sample size: 125 0/1	Log
	Trim / Form / Singulate	Singulate unit	Spec no: 05-03-0521	30x microscope	Every lot	np chart
	Trim / Form / Singulate monitoring	Visual and dimensional inspection	Spec no: 06-02-0520 Including lead spread, standoff and coplanarity	30x microscope Profile projector	1x per day per machine	X-bar-R chart
	QA lot acceptance	Package crack	Spec no : 06-02-0520	Min 30x microscope	Every lot – 45 0/1	Log
	100% Vision inspection		Spec no: 05-03-0527 P05-03-8082	3x scope minimum or auto vision system		Log
	100% Vision Inspection Gate		Spec no : 06-02-0520 P05-03-8082	3x scope	Sample size: 125 0/1	Log
	Pack	Packing & preparation for delivery	Spec no: 05-03-0601 05-03-7300			
	QA Pack buyoff	Visual inspection	Spec no: 06-02-0528			
	Ship to LTC					

Revision A